Thin film soldered SAM on water cooled copper heat sink with 25.0 mm diameter for high power application

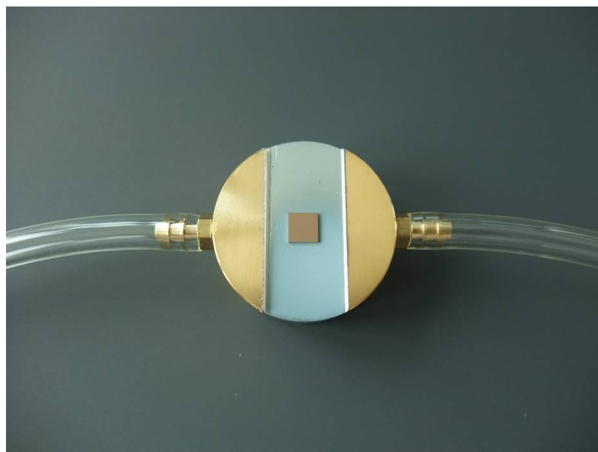
SAM-λ-A-τ-4.0-25.0h-c or SAM-λ-A-τ-4.0-25.0h-e

SAM chip area	standard:	4.0 mm x 4.0 mm
Chip thickness	standard:	450 µm
Front side protection	the SAM is protected with a dielectric front layer.	

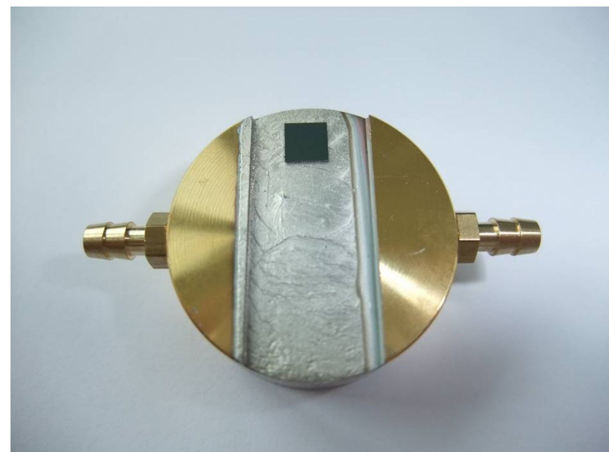
The SAM chip is thin film soldered on a gold plated water cooled copper heat sink with 25.0 mm Ø with In thin film solder. The SAM chip is back side polished and covered with a sputter deposited Ti/Au thin film to ensure a low thermal resistance of ~ 1 K/W to the water cooled copper heat sink.

- The ***standard*** position of the SAM is at the centre of the heat sink → x = 4.0-25.0w-c.
- ***Optional*** the SAM can be mounted on the edge of the heat sink without extra charges → x = 4.0-25.0w-e.

Centre mounted SAM



Edge mounted SAM



Back side

This water cooled heat sink comes with two 1 m long water tubes with an inner diameter of 3 mm.

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